

Surface Mount Technology Association Press Release

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SMTA Announces Lead-Free Soldering Technology Symposium Schedule at SMTA International

Minneapolis, MN - The SMTA announced that the renamed Lead-Free Soldering Technology Symposium will be held on October 20, 2011 as a focused symposium at SMTA International in Ft. Worth, TX. The scope of this year's symposium is the reliability of interconnections, particularly those studied in the second phase of the NASA-DoD Pb-Free Consortium project. The project is providing unprecedented data on the long-term performance of Pb-free interconnections addressing alternative surface finishes as well as the performance of mixed SnPb/Pb-free solder joints and the effects of rework activities.

Session topics include an Overview and Update of the NASA-DoD Lead-Free Electronics Project, Investigating the Edges of Lead-Free Assembly Processes, Mechanical Reliability Performance of Lead-Free Solder Alloys, and the Impact of Alloy Composition, Design and Load Parameters in Lead-Free Solder Joint Reliability.

Papers will be presented by speakers from IBM, Celestica, Boeing, NASA, Rockwell Collins, Alcatel-Lucent and Amkor Technology among others.

"Programmatic Challenges of Pb-Free Technology for the High-Reliability Electronics Industry" is the title of the keynote address given by Paul Vianco, Ph.D., Sandia National Laboratories and symposium chair and co-organizer.

Details of the Lead-Free Soldering Technology Symposium can be found at <http://www.smta.org/smtai/symposium.cfm#lf> or contact SMTA administrator JoAnn Stromberg: 952-920-7682 or joann@smta.org.

The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.

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